

DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:
My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below)
or an original, first and joint inventor (if plural names are listed below) of the subject matter
which is claimed and for which a patent is sought on the invention entitled MULTI-CHIP
WAFER LEVEL SYSTEM PACKAGES AND METHODS OF FORMING SAME, the
specification of which (check one):

- ☐ is attached hereto.
☒ as filed on August 27, 2002 as United States application serial no. 10/229,914 and
was amended on .
☐ as filed on _____ as PCT international application no. _____ and
was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified
specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all
information known to me to be material to the patentability of the subject matter claimed in this
application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d)
or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any
PCT international application(s) designating at least one country other than the United States of
America listed below and on any attached continuation page and have also identified below and
on any attached continuation page any foreign application for patent or inventor's certificate or
any PCT international application(s) designating at least one country other than the United States
of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

			Priority	Claimed
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States
application(s) or § 365(c) of PCT international application(s) designating the United States of
America listed below and on any attached continuation page and, insofar as the subject matter of
each of the claims of this application is not disclosed in any such prior application in the manner
provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to
disclose to the U.S. Patent and Trademark Office all information known to me to be material to
patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available

DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention Title: MULTI-CHIP WAFER LEVEL SYSTEM PACKAGES AND METHODS OF FORMING SAME
between the filing date of such prior application and the national or PCT international filing date
of this application:

_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)
_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United
States provisional application(s) listed below:

_____	_____
(provisional application no.)	(filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and
to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969
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
I hereby declare that all statements made herein of my own knowledge are true and that
all statements made on information and belief are believed to be true; and further that these
statements were made with the knowledge that willful false statements and the like so made are

DECLARATION FOR PATENT APPLICATION
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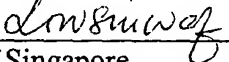
Invention Title: MULTI-CHIP WAFER LEVEL SYSTEM PACKAGES AND METHODS OF FORMING SAME

punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

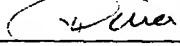
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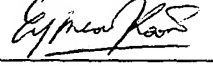
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
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DECLARATION FOR PATENT APPLICATION
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Invention Title: MULTI-CHIP WAFER LEVEL SYSTEM PACKAGES AND METHODS OF FORMING SAME

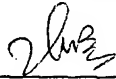
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